A. Interconnect & Package 분과

Room H
하나스퀘어 (B115)

일　시 : 2월 16일(목) 09:30-11:00
세션명 : [TH1-A] 구리 배선 기술
좌　장 : 김형준(연세대학교), 박주상(연세대학교)

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TH1-A-1　09:30-10:00　[Invited]Development of a Diffusion Barrier Layer for Advanced Technology Node of Silicon Devices
저자: J. Koike
소속: Department of Materials Science, Tohoku University

TH1-A-2　10:00-10:15　Conformal Cu Seed Layer Formation by Electroless Deposition in High Aspect Ratio of Non-bosch Through Silicon Vias
저자: Kyung Ju Park, Myung Jun Kim, Taeho Lim, Hyo-Chol Koo, and Jae Jeong Kim
소속: School of Chemical and Biological Engineering, Seoul National University

TH1-A-3　10:15-10:45　[Invited]Development of Ceria-based Slurries at Neutral pH for Cu CMP
저자: Jae Jeong Kim
소속: School of Chemical and Biological Engineering, College of Engineering, Seoul National University